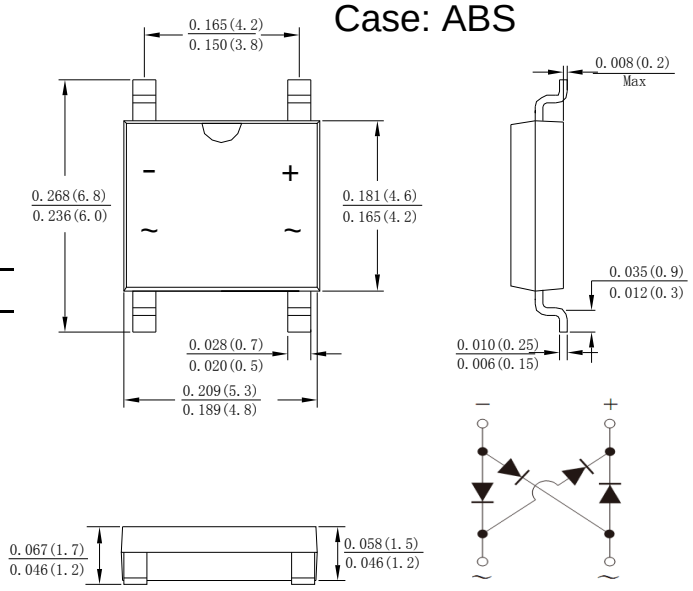
ABS2 THRU ABS10

Single Phase 0.8AMP Surface Mount Glass Passivated Bridge Rectifier

Features

- Glass passivated die construction
- Low forward voltage drop
- High current capability
- High surge current capability
- Designed for surface mount application
- Plastic material-UL flammability 94V-0

Case: ABS



Dimensions in inches and (millimeters)

Mechanical Data

- Case: SOPA-4, molded plastic ABS
- Terminals: plated leads solderable per MIL-STD-202, Method 208
- Polarity: as marked on case
- Mounting position: Any
- Marking: type number

Maximum Ratings and Electrical Characteristics

Rating at 25℃ ambient temperature unless otherwise specified.
Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	SYMBOL	ABS2	ABS4	ABS6	ABS8	ABS10	UNITS
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_{DC}	200	400	600	800	1000	V
RMS Reverse Voltage	V_{RMS}	140	280	420	560	700	V
Average Rectified Output Current (Note 1)@T_c=100℃ (Note 2)@T_c=100℃	IF(AV)	0.5 0.8					A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30					A
I^2t Rating for Fusing (t < 8.3ms)	I^2t	3.74					A^2s
Forward Voltage per element @IF=0.5A @IF=0.8A	V_{FM}	0.95 1.0					V
Peak Reverse Current At Rated DC Blocking Voltage @T_J =25℃ @T_J =125℃	I_R	5.0 100					uA
Typical Junction Capacitance (Note3)	C_J	13					pF
Typical Thermal Resistance	$R_{\theta JA}$ $R_{\theta JL}$	62.5 25					℃/W
Operating and Storage Temperature Range	T_J,T_{STG}	-55to+150					℃

Note:1. Mounted on glass epoxy PC board with 1.3mm^2 solder pad.
2. Mounted on aluminum substrate PC board with 1.3mm^2 solder pad.
3. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

FIG.1 MAXIMUM FORWARD CURRENT DERATING CURVE

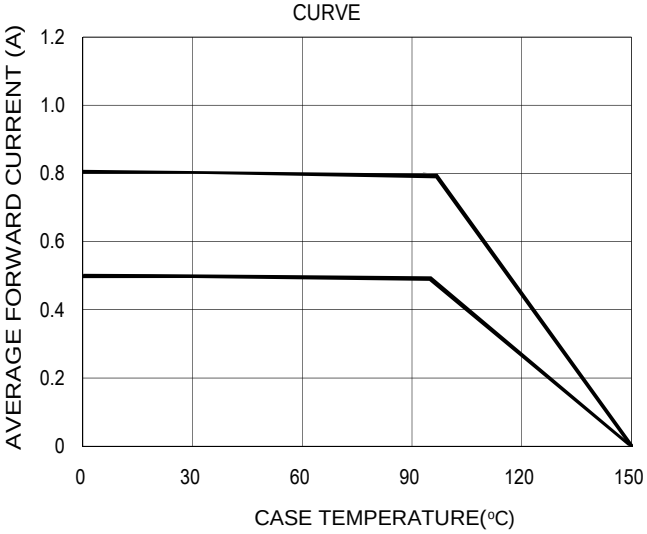


FIG. 2 TYPICAL FORWARD CHARACTERISTIC

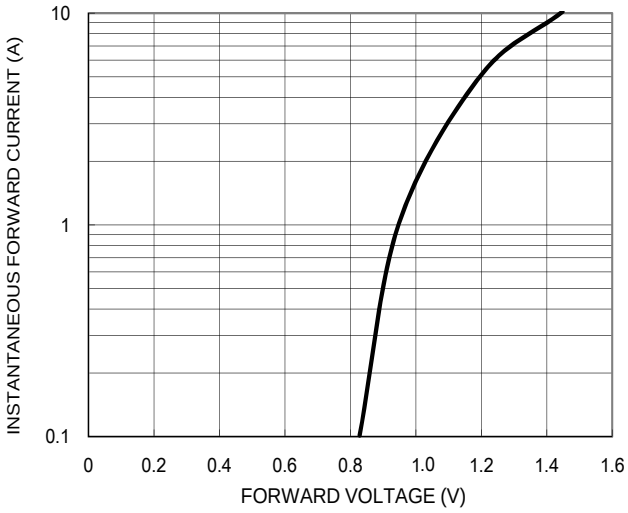


Fig. 3 Maximum Peak Forward Surge Current

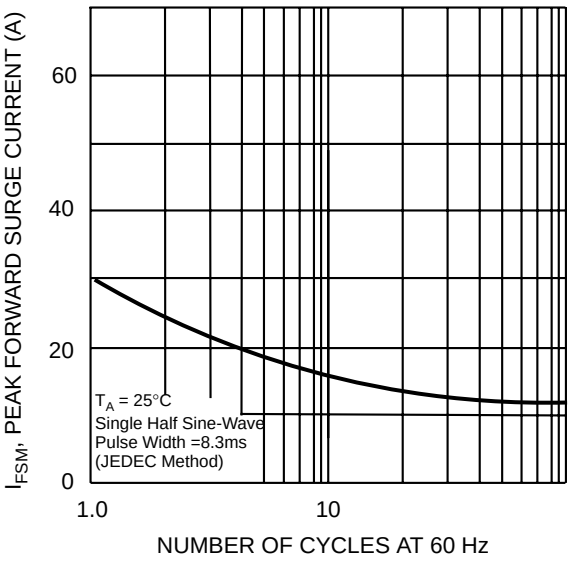


Fig. 4 Typical Reverse Characteristics

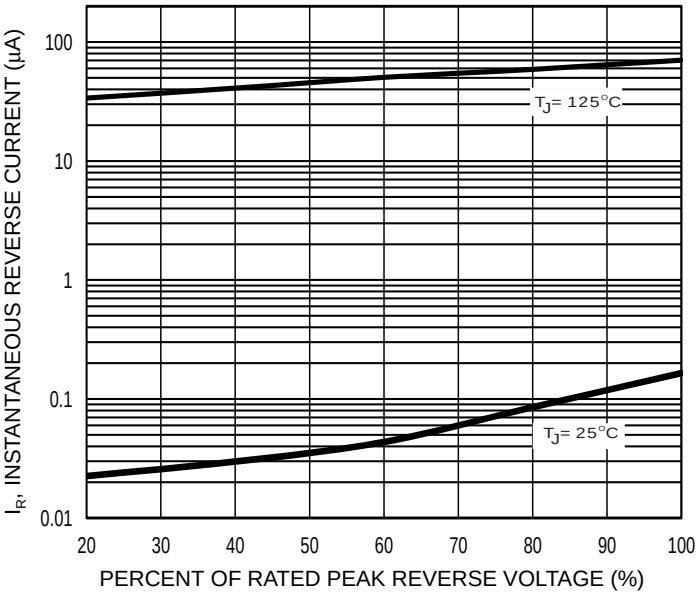
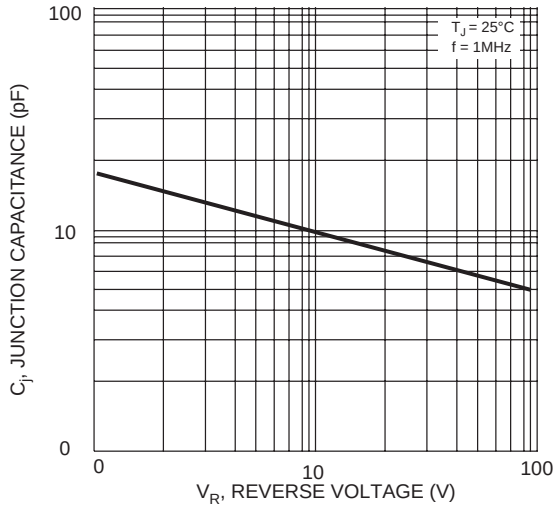
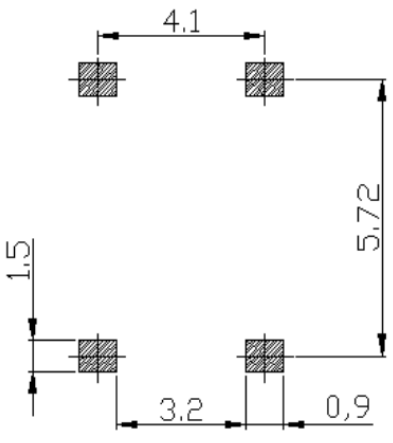


Fig. 5 Typical Junction Capacitance



PAD LAYOUT



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